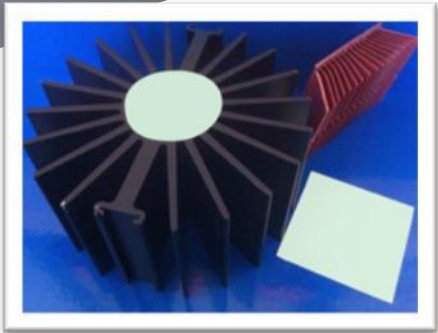


# UniGap 1100ES

## Soft Gap Filler



UniGap 1100ES is an extremely soft and ceramic-filled silicone gap filler, designed to thermally couple a wide range of heat dissipating components.

UniGap 1100ES is robust and compressible over an extensive range of stack up tolerances where minimal pressure forces are exerted onto component parts. The material can be supplied with a fabric or film liner on one side for additional guaranteed electrical isolation and to provide greater cut through resistance.

### Features

- Extremely soft and compliant silicone gap filler
- Thermal conductivity = 1.1 W/mK
- Exerts very low pressures to devices and components when in operation
- Provides good electrical isolation

### Availability

- Thicknesses of 0.5mm to 6.0mm in steps of 0.5mm
- Available as custom die-cut shapes and forms on request and submission of drawing
- Standard sheet sizes of 609mm x 609mm
- Tacky surfaces are available on one or both sides

### Typical Physical Properties

| Property (unit)                                  | Test Method | UniGap 1100ES (2.5mm) |
|--------------------------------------------------|-------------|-----------------------|
| Colour                                           | Visual      | Pale Green            |
| Thickness (mm)                                   | In House    | 0.5-5.0               |
| Thermal Conductivity (W/mK)                      | ASTM D5470  | 1.1                   |
| Hardness (Shore 00)                              | ASTM D2240  | 27                    |
| Thermal Impedance (°C in. <sup>2</sup> /W) @ 50% | ASTM D5470  | 1.75                  |
| Operating Temp. (°C)                             | -           | -55 to +200           |
| Flame Rating                                     | UL94        | V-0                   |

### Benefits

- Soft and conformable enabling usage with components of multiple heights and sizes with a single pad
- Supplied with a release liner on both sides and also with a fabric or film on one side for easy handling
- Maintains optimal performance over a wide range of temperatures

### Recommended Uses

- Typically used in any gap filler application where multiple component height and size differences exist
- Memory cards and VGA modules
- Cooling digital signal processing (DSP) units
- Cooling power devices in AC-DC and DC-DC PSUs

### Electrical and Mechanical Information

| Property (unit)                          | Test Method | UniGap 1100ES          |
|------------------------------------------|-------------|------------------------|
| Dielectric Strength (kV/mm)              | ASTM D149   | > 9.5                  |
| Deflection Force (kPa) @ 50% 2.5mm thick | -           | 100                    |
| Volume Resistivity (Ω-cm)                | ASTM D257   | 2.0 x 10 <sup>10</sup> |